

Rev. V1

Features

- Low Junction Capacitance for Low Insertion Loss and High Isolation: C_T6 <0.3 pF
- Low Series Resistance for High Isolation: R_S <1 Ω
- Nominal I layer width : W = 10 μm
- · Compact surface mount plastic package
- RoHS* Compliant

Description

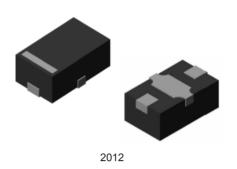
The MLP7120-2012 limiter PIN diode is a low series resistance The MLP7120-2012 limiter PIN diode is a low series resistance, low capacitance limiter PIN diode packaged in a surface mount, low-parasitic plastic package. It is manufactured using a proprietary diode process for excellent performance and high reliability.

The 10 μm nominal I layer width of this diode produces a threshold level of 20 dBm nominal, for demanding receiver protection applications. The low series resistance (<1 Ω), and low total capacitance (<0.3 pF) of MLP7120-2012 produce excellent isolation and insertion loss in shunt, receiver protection applications.

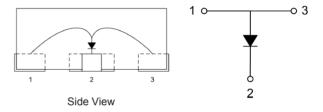
The MLP7120-2012 limiter PIN diode is designed to be used in receiver protection applications.



| Part Number | Package |
|----------------|-----------------------|
| MLP7120-2012-R | 3000 piece reel |
| MLP7120-2012-B | 100 per bag bulk |
| MLP7120-2012-W | 400 piece waffle pack |



Pin Out / Schematic



Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM Class 0 devices.

Moisture Sensitivity

These electronic devices are rated MSL 1.

Environmental Capabilities

Capable of meeting the environmental requirements of MIL-STD-750 and MIL-STD-883.

* Restrictions on Hazardous Substances, European Union Directive 2011/65/EU.



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Electrical Specifications: $T_A = +25$ °C (measured on evaluation board)

| Parameter | Test Conditions | Units | Min. | Тур. | Max. |
|--|---|-------|------|------------|------|
| Breakdown Voltage (V _B) | I _R = 10 μA | V | 120 | _ | 180 |
| Forward Voltage (V _F) | I _F = 100 mA | V | _ | 0.95 | 1.2 |
| Total Capacitance ¹ (C _T) | V _R = 6 V, 1 MHz | pF | _ | _ | 0.3 |
| Series Resistance ² (R _S) | I _F = 1 mA, 1 GHz I _F = 10 mA, 1 GHz | Ω | _ | 3.5 1.0 | _ |
| Recovery Time (T _R) | End of the RF input to 1 dB excess insertion loss | ns | _ | 50 | _ |
| Minority Carrier Lifetime (T _L) | 50% control to 90% output voltage, $I_F = 10 \text{ mA}$, $I_R = 6 \text{ mA}$, 1 KHz | ns | _ | 50 | _ |
| Thermal Resistance (θ _{JC}) | _ | °C/W | _ | _ | 45 |
| I layer Thickness (W) | _ | μm | _ | 10 | _ |

^{1.} Total capacitance (C_T) is the sum of the diode junction capacitance (C_J) and the package capacitance (C_{PKG}) . 2. Series resistance (R_S) is measured on the HP 4291 Impedance Analyzer.

Absolute Maximum Ratings

| Parameter | Test Conditions | Absolute Maximum | |
|-----------------------|-------------------------------------|------------------|--|
| Forward DC Current | _ | 150 mA | |
| Reverse DC Voltage | _ | 180 V | |
| Forward DC Voltage | I _F = 150 mA | 1.3 V | |
| Peak RF Input Power | Pulse Width = 1 μs, Duty Cycle = 1% | 60 dBm | |
| CW Input Power | _ | 37 dBm | |
| Junction Temperature | _ | +175°C | |
| Operating Temperature | _ | -55°C to +150°C | |
| Storage Temperature | _ | -65°C to +100°C | |
| Assembly Temperature | t = 10 s | +260°C | |



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Assembly Instructions

Diodes may be placed onto circuit boards with pick and place manufacturing equipment from tape-reel. The devices are attached to the circuit using conventional solder re-flow or wave soldering procedures with RoHS type or Sn 60 / Pb 40 type solders.

Table 1. Time-Temperature Profile for Sn60/Pb40 or RoHS Type Solders

| Profile Feature | SnPb Solder Assembly | Pb-Free Solder Assembly | |
|--|------------------------------|------------------------------|--|
| Average Ramp-Up Rate (T _L to T _P) | 3°C /second maximum | 3°C /second maximum | |
| Preheat: -Temperature Min (T _{SMIN}) -Temperature Max (T _{SMAX}) -Time (min to max)(t _S) | 100°C 150°C 60 - 120 s | 150°C 200°C 60 - 180 s | |
| T _{SMAX} to T _L - Ramp-Up Rate | | 3°C /s maximum | |
| Time Maintained Above: -Temperature (T_L) - Time (t_L) | 183°C 60 - 150 s | 217°C 60 - 150 s | |
| Peak temperature (T _P) | 225 +0/-5°C | 260 +0/-5°C | |
| Time Within 5°C of Actual Peak Temperature (t _P) | 10 – 30 s | 20 – 40 s | |
| Ramp-Down Rate | 6°C /s maximum | 6°C /s maximum | |
| Time 25°C to Peak Temperature | 6 minutes maximum | 8 minutes maximum | |

Critical Zone T_L to T_P Ramp Up **Temperature** TSMAX

t_s Preheat

t 25°C to Peak Time

Figure 1. Solder Re-Flow Time-Temperature Profile

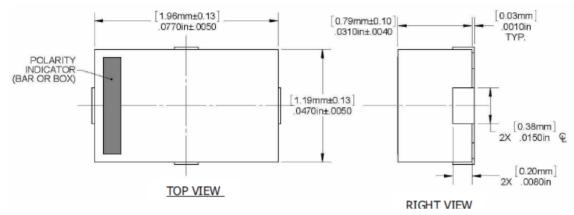
Ramp Down

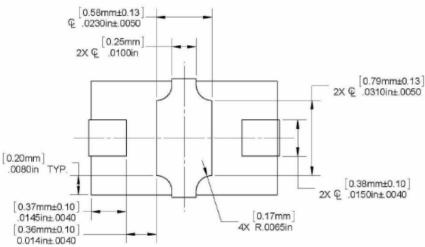
TSMIN



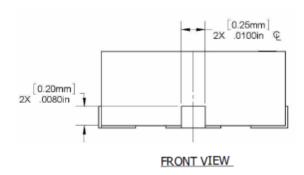
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Outline (2012)

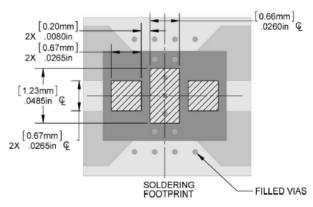




BOTTOM VIEW



Suggested PCB Footprint



MLP7120-2012



Surface Mount Limiter PIN Diode

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